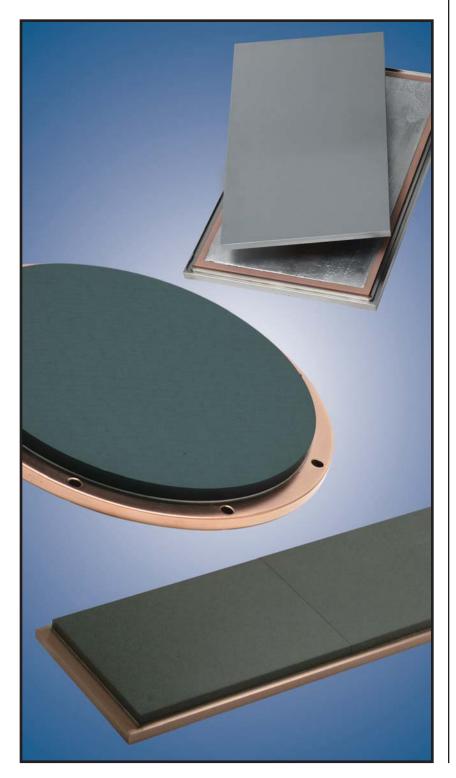
# Indium Bonding | Kurt J. Lesker

# **Service**





# **Applications**

· Sputtering target and backing plate bonding

### **Features**

- Highest thermally conductive bond offered
- · Thorough bond coverage
- Malleable solder allows for thermal expansion during sputtering
- Provides support for fragile target materials
- Compatible with a wide range of target materials

# **Bonding Process**

- Target bonding surface may be coated prior to bonding to improve adhesion
- Indium reflow process provides complete bond coverage
- · Accurate alignment of target on backing plate
- Bonded target assemblies are cleaned and ready for use in vacuum

# **Options**

- · Wide range of sizes and shapes
- Multi-tile assemblies
- Complex backing plate configurations
- · Compatible with most target materials

# **Specifications**

Maximum Operating Temperature	150°C
Thermal Conductivity	83 W/m·K
Coefficient of Thermal Expansion	32.1 x 10 <sup>-6</sup> K <sup>-1</sup>
Electrical Resistivity	8 x 10 <sup>-6</sup> ohm-cm
Bond Coverage	>95%
Bond Line Thickness	0.010"-0.020"
Bond Line Thickness Tolerance	± 0.003"

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